

**CONTACT METALLIZATION**

Top Contact: 22,000  
A Aluminum

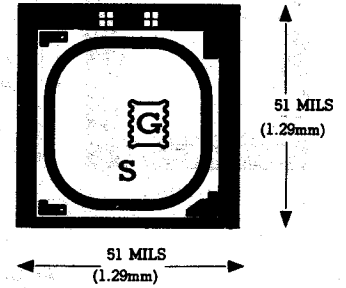
Backside Contact: 3,000 A Gold

**ASSEMBLY RECOMMENDATIONS**

It is advisable that:

- a) the chip be eutectically mounted with gold silicon preform 98/2%.
- b) 8 mil aluminum wire be ultrasonically attached to the top contact.

CHIP NUMBER  
SVN101



Die Size: 51x51 (mils)  
1.29x1.29 (mm)  
Pad Size: 20x40 (mils)  
0.51x1.02 (mm)

**CONTACT METALLIZATION**

Top Contact: 22,000  
A. Aluminum

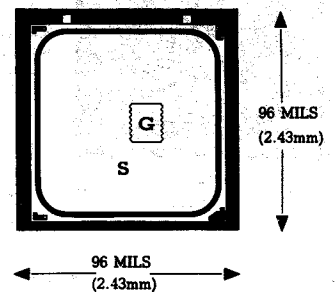
Backside Contact: 3,000 A Gold

**ASSEMBLY RECOMMENDATIONS**

It is advisable that:

- a) the chip be eutectically mounted with gold silicone preform 98/2%.
- b) 8 mil aluminum wire be ultrasonically attached to the top contact.

CHIP NUMBER  
SVN105



Die Size: 96x96 (mils)  
2.43x2.43 (mm)  
Pad Size: 20x40 (mils)  
0.51x1.02 (mm)